

ABSTRACT OF THE DISCLOSURE

POLISHING APPARATUS AND POLISHING METHOD

5 A polishing apparatus capable of accurately detecting a change in wafer condition
is disclosed. The polishing apparatus includes: a polishing table for supporting a polishing
pad having a polishing surface; a rotatable head body having a pressing surface arranged to
press a wafer against the polishing surface; a retainer ring surrounding the pressing surface,
the retainer ring being rotatable together with the head body and arranged to press the
10 polishing surface; a non-rotating member that does not rotate together with the retainer ring;
a vibration transmission member in contact with both the retainer ring and the non-rotating
member; and a sensor secured to the non-rotating member.

FIG. 4